

# NSR05F30NXT5G

## Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

### Features

- Low Forward Voltage Drop – 400 mV @ 500 mA
- Low Reverse Current – 15  $\mu$ A @ 10 V VR
- 500 mA of Continuous Forward Current
- ESD Rating – Human Body Model: Class 3B  
– Machine Model: Class C
- High Switching Speed
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

### Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	30	V
Forward Current (DC)	$I_F$	500	mA
Forward Surge Current (60 Hz @ 1 cycle)	$I_{FSM}$	10	A
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	$I_{FRM}$	4.0	A
ESD Rating: Human Body Model Machine Model	ESD	> 8 > 400	kV V

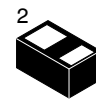
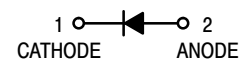
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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## 30 V SCHOTTKY BARRIER DIODE



**DSN2  
(0402)  
CASE 152AC**

### MARKING DIAGRAM

PIN 1



05F30 = Specific Device Code

YYY = Year Code

### ORDERING INFORMATION

Device	Package	Shipping†
NSR05F30NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NSR05F30NXT5G

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$ $P_D$			240 521	$^\circ\text{C}/\text{W}$ mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$ $P_D$			94 1.3	$^\circ\text{C}/\text{W}$ W
Storage Temperature Range	$T_{stg}$			-40 to +125	$^\circ\text{C}$
Junction Temperature	$T_J$			+150	$^\circ\text{C}$

1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
2. Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Leakage ( $V_R = 10\text{ V}$ ) ( $V_R = 30\text{ V}$ )	$I_R$			15 75	$\mu\text{A}$
Forward Voltage ( $I_F = 100\text{ mA}$ ) ( $I_F = 500\text{ mA}$ )	$V_F$		0.320 0.400	0.360 0.430	V

# NSR05F30NXT5G

## TYPICAL CHARACTERISTICS

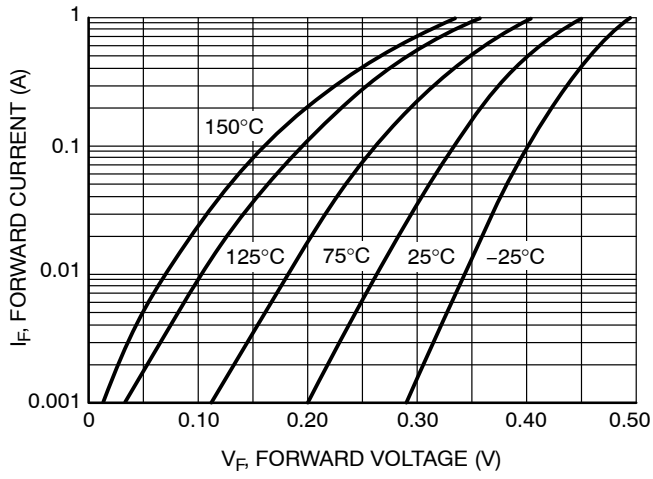


Figure 1. Forward Voltage

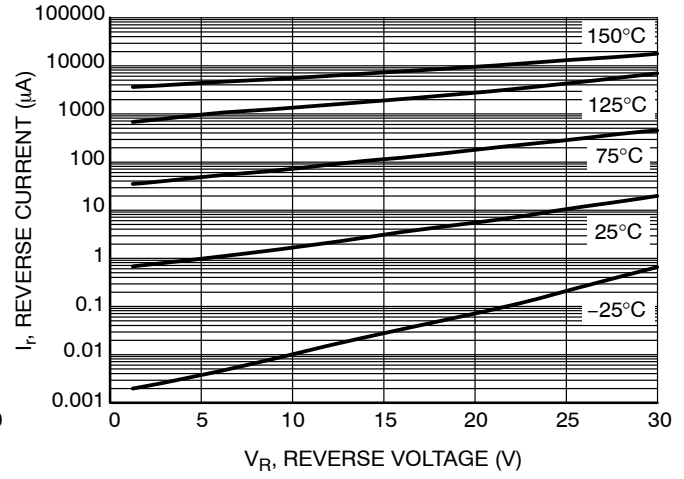


Figure 2. Leakage Current

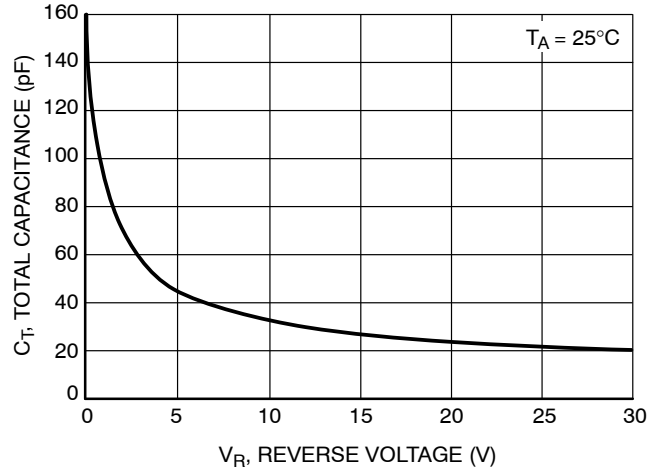


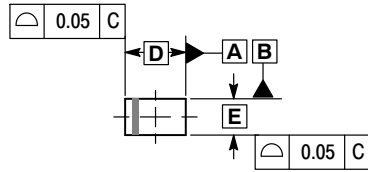
Figure 3. Total Capacitance



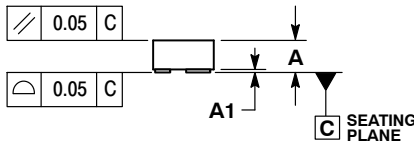
SCALE 8:1

**DSN2, 1.0x0.6, 0.575P, (0402)**  
 CASE 152AC  
 ISSUE D

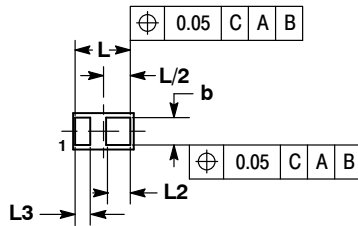
DATE 27 APR 2017



TOP VIEW

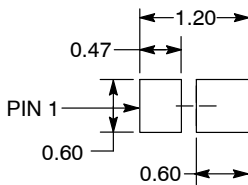


SIDE VIEW



BOTTOM VIEW

**RECOMMENDED  
 SOLDER FOOTPRINT\***



DIMENSIONS: MILLIMETERS

See Application Note AND8464/D for more mounting details

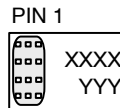
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

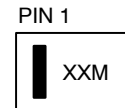
MILLIMETERS		
DIM	MIN	MAX
A	0.25	0.31
A1	---	0.05
b	0.45	0.55
D	1.00 BSC	
E	0.60 BSC	
L	0.85	0.95
L2	0.35	0.45
L3	0.20	0.30

**GENERIC  
 MARKING DIAGRAM1\***



XXXX = Specific Device Code  
 YYY = Year Code

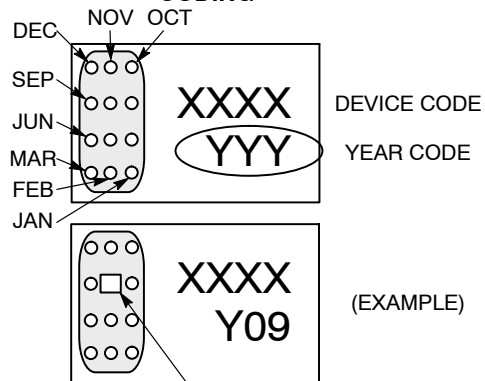
**GENERIC  
 MARKING DIAGRAM2\***



XX = Specific Device Code  
 M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

**CATHODE BAND MONTH  
 CODING**



INDICATES AUG 2009

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